

AMENDMENT TRANSMITTAL LETTER				Docket No. M0659.0002	
Application No. 10/789,423-Conf. #5684		Filing Date February 27, 2004		Examiner B. P. Sandvik	
				Art Unit 2826	
Applicant(s): Harald Bottnar et al.					
Invention: SOLDER, MICROELECTROMECHANICAL COMPONENT AND DEVICE, AND A PROCESS FOR PRODUCING A COMPONENT OR DEVICE					
TO THE COMMISSIONER FOR PATENTS					
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	22	- 22 =		x	
Independent Claims	7	- 7 =		x	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify): Extension for response within third month					1,020.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					1,020.00
<input checked="" type="checkbox"/> Large Entity <input type="checkbox"/> Small Entity					
<input type="checkbox"/> No additional fee is required for this amendment.					
<input type="checkbox"/> Please charge Deposit Account No. <u>50-2215</u> in the amount of \$ _____. A duplicate copy of this sheet is enclosed.					
<input type="checkbox"/> A check in the amount of \$ _____ to cover the filing fee is enclosed.					
<input checked="" type="checkbox"/> Payment by credit card.					
<input checked="" type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. <u>50-2215</u> as described below. A duplicate copy of this sheet is enclosed.					
<input checked="" type="checkbox"/> Credit any overpayment.					
<input checked="" type="checkbox"/> Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.					
Laura C. Brutman Attorney/Agent Reg. No.: 38,395				Dated: <u>September 19, 2007</u>	
DICKSTEIN SHAPIRO LLP 1177 Avenue of the Americas New York, New York 10036-2714 (212) 277-6592					
I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filing system in accordance with § 1.6(a)(4). Dated: <u>7/19/2007</u> Signature: (Laura C. Brutman)					

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Harald Bottner et al.

Application No.: 10/789,423

Confirmation No.: 5684

Filed: February 27, 2004

Art Unit: 2826

For: SOLDER, MICROELECTROMECHANICAL
COMPONENT AND DEVICE, AND A
PROCESS FOR PRODUCING A
COMPONENT OR DEVICE

Examiner: B. P. Sandvik

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated March 26, 2007, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.